

WHAT IS CLAIMED IS:

1. A method for manufacturing an electronic part characterized by that a layer having a uniform thickness is formed by forming a conductor portion on
5 a surface of a support member, bringing an insulating sheet into contact with said conductor portion from above, and pressing said insulating sheet to the height of said conductor portion using said conductor portion as a stopper to make the height of said
10 insulating sheet equal to the height of said conductor portion.

2. A method for manufacturing an electronic part characterized by that a layer having a uniform
15 thickness is formed by forming a conductor portion on a surface of a support member, bringing an insulating sheet into contact with said conductor portion from above, pressing said insulating sheet to the height of said conductor portion using said conductor
20 portion as a stopper to make the height of said insulating sheet equal to the height of said conductor portion, and then detaching said conductor portion and said insulating sheet from said surface.

25 3. A method for manufacturing an electronic part characterized by that a layer having a uniform thickness is formed by forming a power supply film on

a surface of a support member, forming a conductor portion by plating using the power supply film as an electrode, bringing an insulating sheet into contact with said conductor portion from above, pressing said
5 insulating sheet to the height of said conductor portion using said conductor portion as a stopper to make the height of said insulating sheet equal to the height of said conductor portion, then detaching said conductor portion and said insulating sheet from said
10 surface, and removing said power supply film.

4. A method for manufacturing an electronic part according to any one of claims 1 to 3, wherein a B-stage sheet is used as said insulating sheet.

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5. A method for manufacturing an electronic part according to any one of claims 1 to 3, wherein a thermoplastic insulating sheet is used as said insulating sheet.

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6. A method for manufacturing an electronic part according to any one of claims 1 to 3, wherein heating is performed in addition to said pressing.

25 7. An electronic part comprising, at least, a conductor portion having an interior completely filled up and rising from vertically from a surface

of a support member and an insulating layer
surrounding the circumference of said conductor
portion and having a thickness equal to said
conductor portion, said conductor portion and said
5 insulating layer forming a layer having a uniform
thickness.

8. An electronic part comprising, at least, a
conductor portion having an interior completely
10 filled up and rising from vertically from the bottom
of a support member and an insulating layer
surrounding the circumference of said conductor
portion and having a thickness equal to said
conductor portion, said conductor portion and said
15 insulating layer forming a layer having a uniform
thickness.

9. An electronic part according to claim 7 or 8,
wherein said conductor portion is formed by plating.